

AMENDMENTS TO THE CLAIMS

1. (ORIGINAL) A process for forming a conductive layer on a substrate, comprising the steps of depositing ink on the substrate by means of lithographic printing to form a seeding layer, and depositing a first electrically conducting layer on the seeding layer by electroless deposition.
2. (ORIGINAL) A process as claimed in claim 1, comprising the step of electroplating a second electrically conducting layer onto the first electrically conducting layer.
- 3.-18. (CANCELLED)
19. (PREVIOUSLY PRESENTED) The process of claim 2 further comprising the step of attaching an electrical component to the first or second conducting layer by means of a conductive polymer adhesive.
20. (PREVIOUSLY PRESENTED) The process of claim 1 wherein the substrate is formed from a polymer into a flexible sheet.
21. (PREVIOUSLY PRESENTED) The process of claim 1 wherein the substrate is coated with a copolymer adhesive.
22. (PREVIOUSLY PRESENTED) The process of claim 1 wherein the ink comprises a particulate material suspended in a mixture of a resin and an organic solvent.
23. (PREVIOUSLY PRESENTED) The process of claim 22 wherein the particulate material is a metal or carbon.

24. (PREVIOUSLY PRESENTED) The process of claim 22 wherein the resin is a polymer having amide groups.
25. (PREVIOUSLY PRESENTED) The process of claim 1 wherein the thickness of the seeding layer is from 3 to 5 microns.
26. (PREVIOUSLY PRESENTED) The process of claim 1 wherein the thickness of the first electrically conducting layer is less than or equal to 4 microns.
27. (PREVIOUSLY PRESENTED) The process of claim 1 wherein the thickness of the first electrically conducting layer is about 0.25 microns.
28. (PREVIOUSLY PRESENTED) The process of claim 1 wherein the first electrically conducting layer is formed from at least one of copper, palladium, silver, gold, platinum, or nickel.
29. (PREVIOUSLY PRESENTED) The process of claim 1 further comprising the step of soldering an electrical component on the substrate.
30. (PREVIOUSLY PRESENTED) The process of claim 1 further comprising the step of attaching an electrical component to the first conducting layer by means of a conductive polymer adhesive.
- 31.-33. (CANCELLED)

34. (PREVIOUSLY PRESENTED) A lithographic ink for use in a lithographic printing process onto a polymer substrate, the ink comprising a particulate material suspended in a mixture of a resin, an antioxidant, and an organic solvent, wherein the resin comprises a polyamide.
35. (PREVIOUSLY PRESENTED) An ink as claimed in claim 34 wherein the particulate material is a metal or carbon.